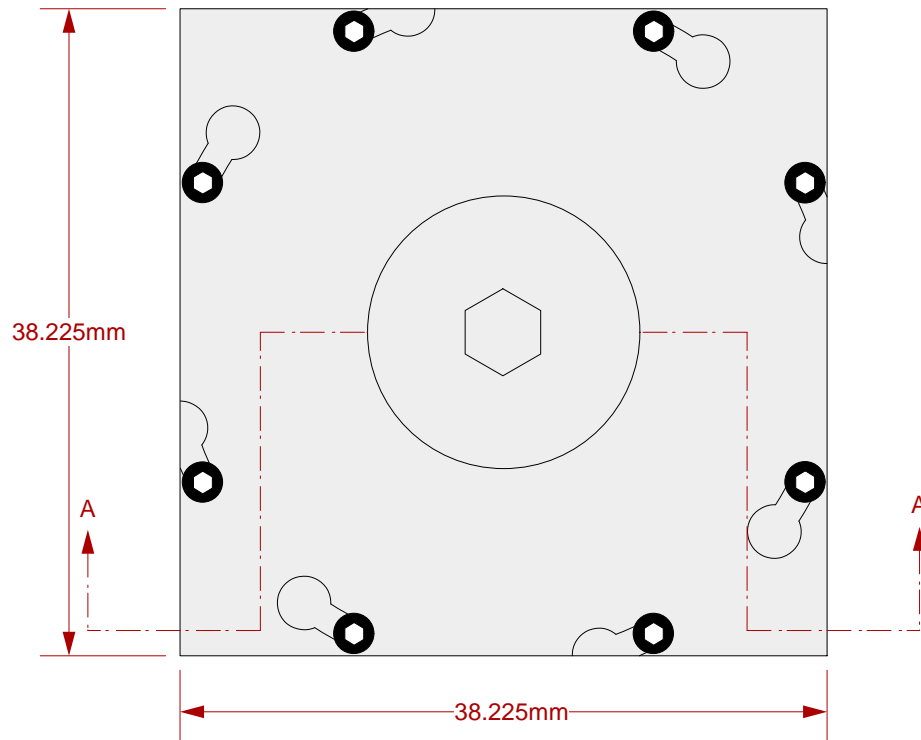


GHz BGA Socket - Direct mount, solderless

Features

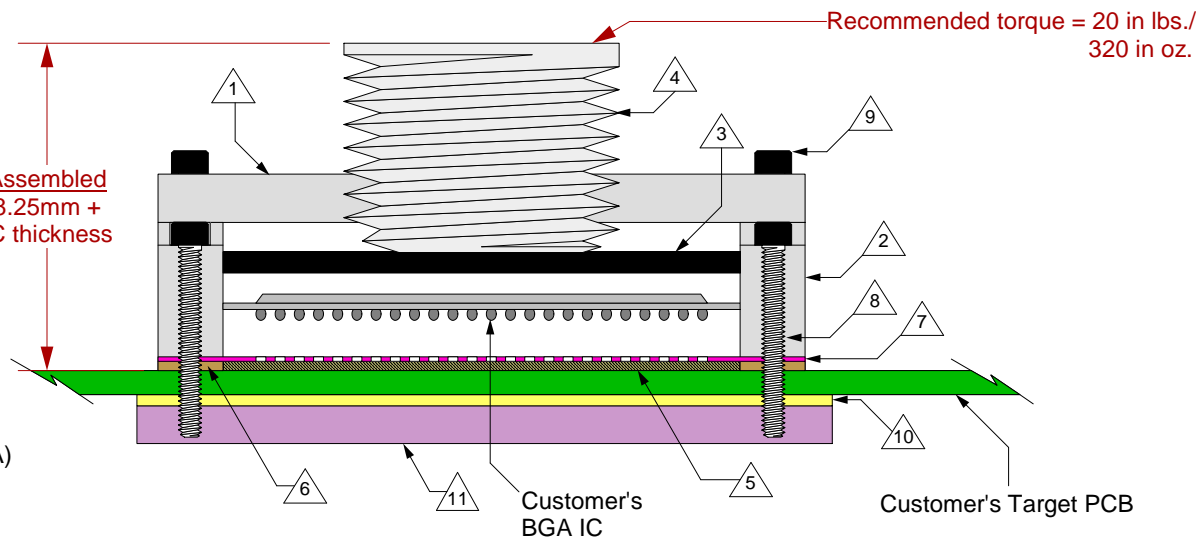
- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Top View



Assembled
8.25mm +
IC thickness

Side View
(Section AA)



- | | |
|----|--|
| 1 | Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm. |
| 2 | Socket base: Black anodized Aluminum.
Thickness = 6.5mm. |
| 3 | Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm. |
| 4 | Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm. |
| 5 | Elastomer: 40 micron dia gold plated brass
filaments arranged symmetrically in a silicone
rubber (63.5 degree angle).
Thickness = 0.75mm. |
| 6 | Elastomer Guide: Cirlex or equivalent.
Thickness = 0.75mm. |
| 7 | Ball Guide: Kapton polyimide. |
| 8 | Socket base screw: Socket head cap, alloy steel with
black oxide finish, 0-80 fine thread, 12.7mm long. |
| 9 | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine
thread. |
| 10 | Backing Plate: Black anodized Aluminum.
Thickness = 6.35mm. |
| 11 | Insulation Plate: FR4/G10, Thickness = 6.35mm. |

SG-BGA-6037 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: F

Drawing: W. Watson

Date: 3/11/02

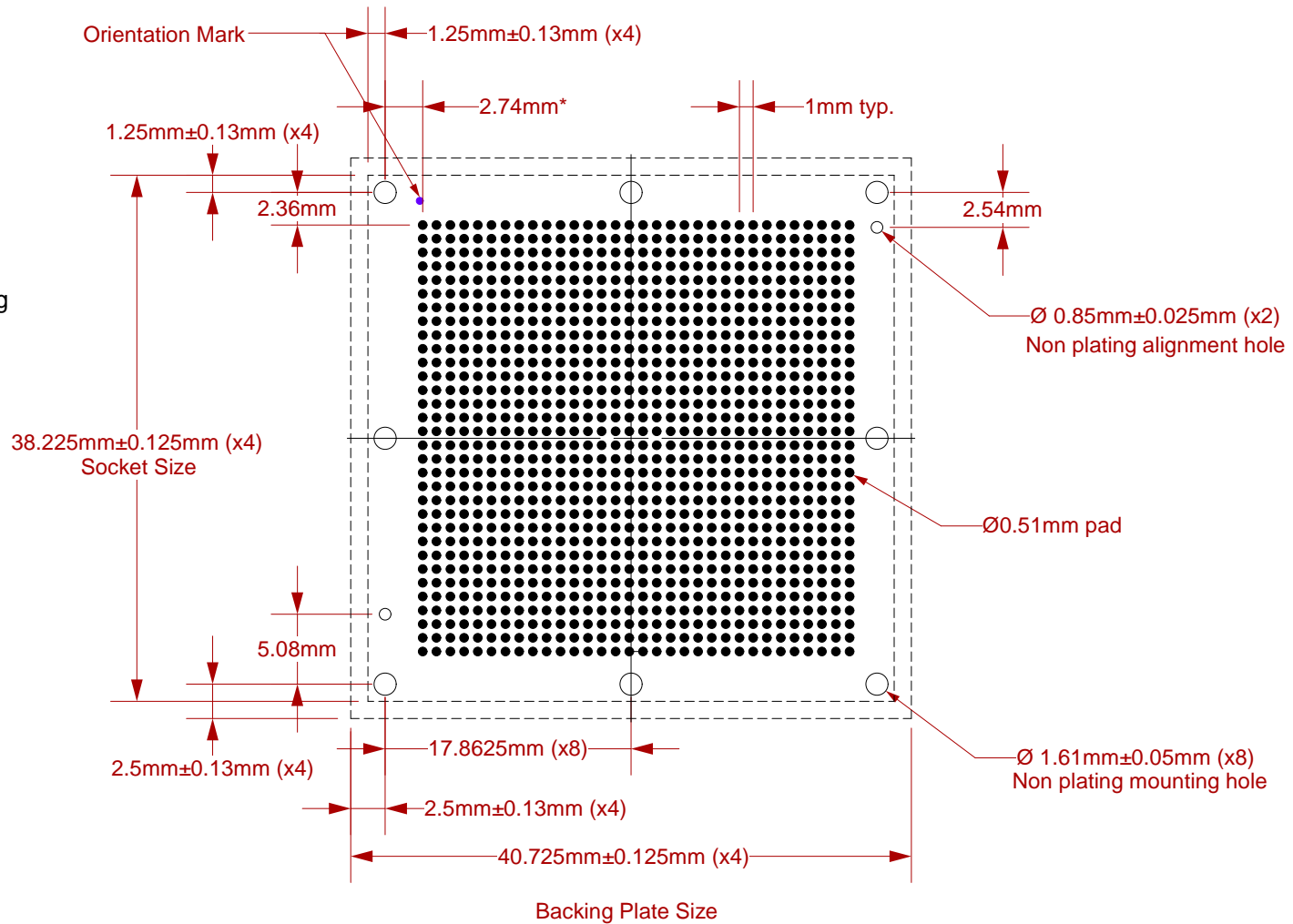
File: SG-BGA-6037 Dwg

Modified: 7/16/09, AE

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.




Target PCB Recommendations

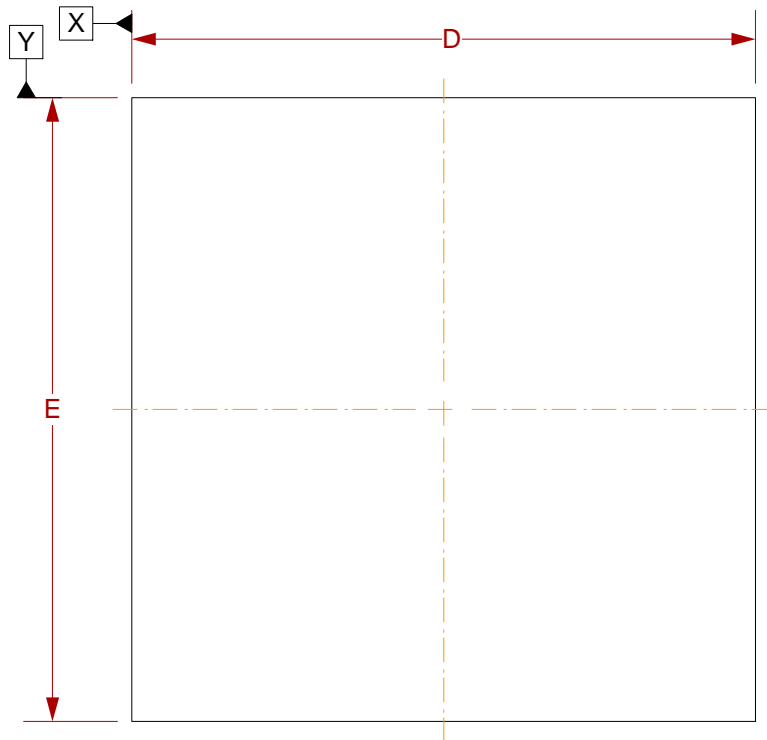
Total Thickness: 2.4mm min.
Plating: Gold or Solder finish.
PCB Pad Height: Same or higher than solder mask.

NOTE: Steel backing plate may be required based on end user's application

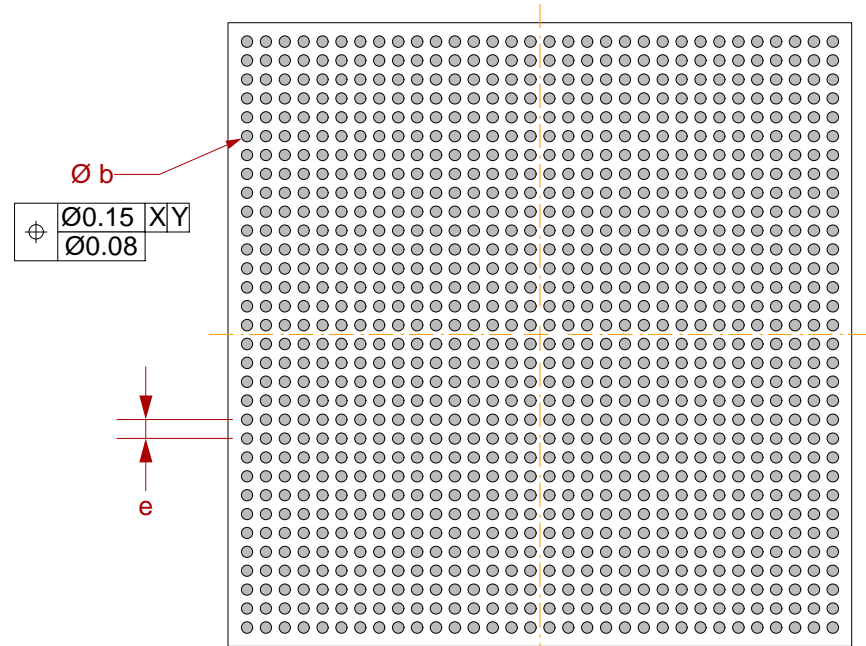
Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

	SG-BGA-6037 Drawing		Status: Released	Scale: 2:1	Rev: F
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com		Drawing: W. Watson		Date: 3/11/02
			File: SG-BGA-6037 Dwg	Modified: 7/16/09, AE	

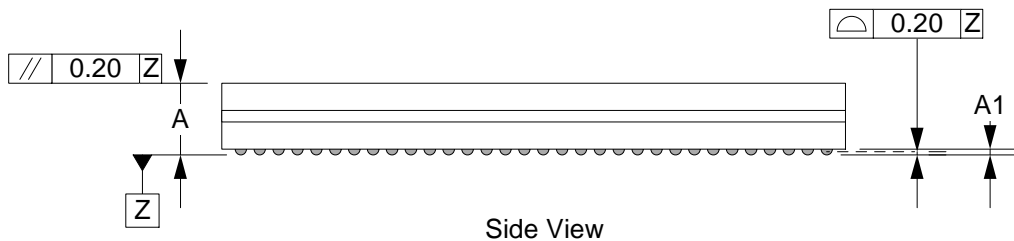
Compatible BGA Spec



Top View



Bottom View




Side View

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

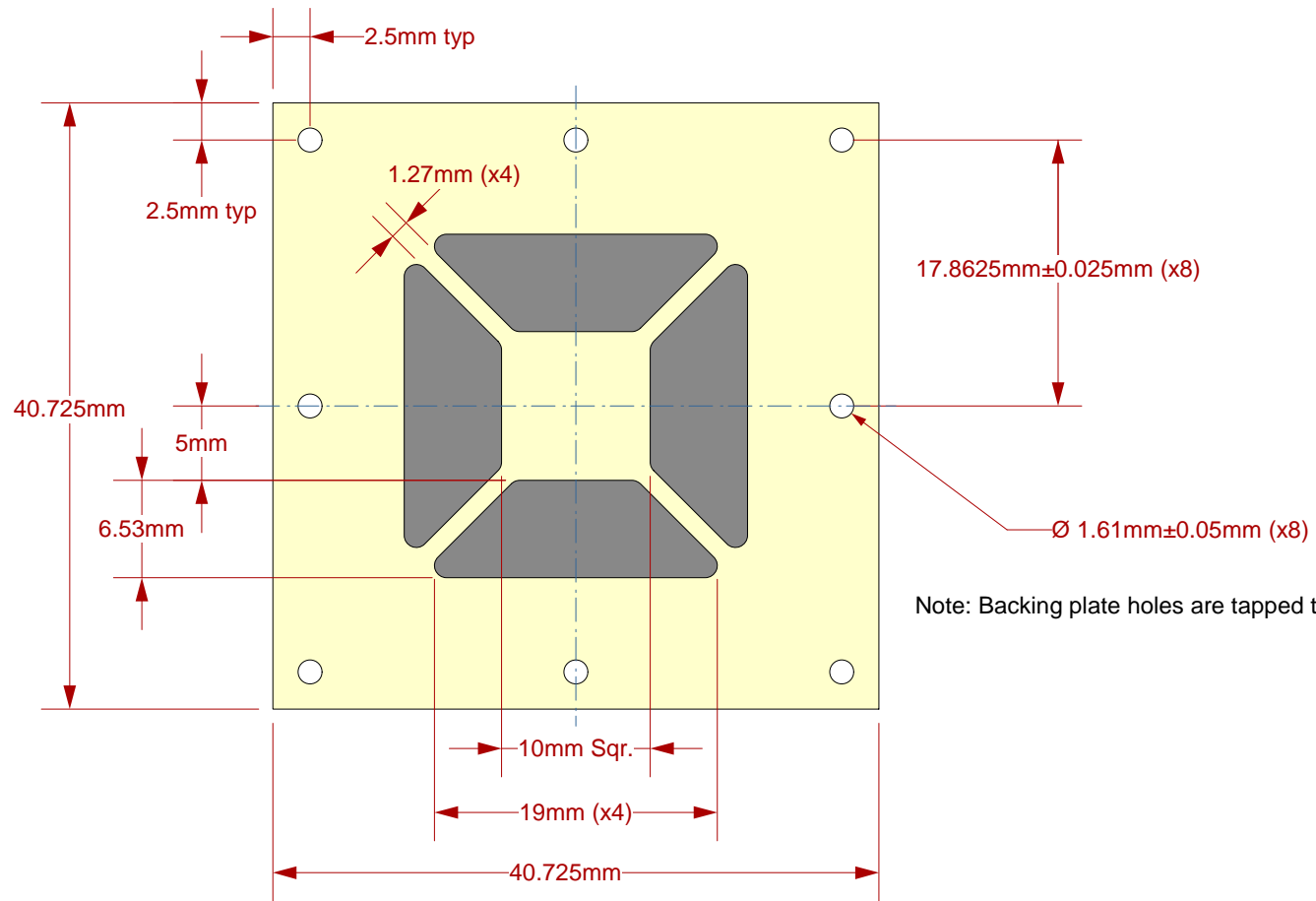
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.5
A1	0.3	0.5
b	0.5	0.7
D	32.8	33.2
E	32.8	33.2
e	1.0 BSC	

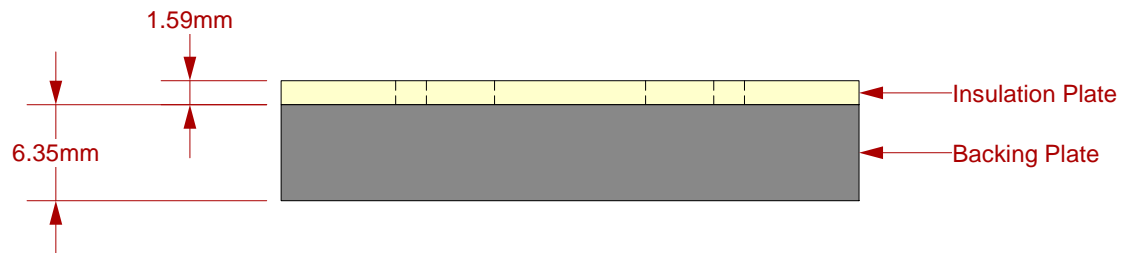
Array: 32x32

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	<p>Drawing: W. Watson</p>		<p>Date: 3/11/02</p>		
	<p>File: SG-BGA-6037 Dwg</p>		<p>Modified: 7/16/09, AE</p>		


Top View



Side View



Description: Insulation Plate and Backing Plate

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	<p>Drawing: W. Watson</p>	<p>Date: 3/11/02</p>		
		<p>Modified: 7/16/09, AE</p>		